PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4954447

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HUI WANG	03/30/2018
FUFA CHEN	03/30/2018
FUPING CHEN	04/04/2018
JIAN WANG	04/02/2018
XI WANG	03/30/2018
XIAOYAN ZHANG	03/30/2018
YINUO JIN	03/30/2018
ZHAOWEI JIA	04/16/2018
LIANGZHI XIE	04/18/2018
JUN WANG	03/30/2018
XUEJUN LI	03/30/2018

RECEIVING PARTY DATA

Name:	ACM RESEARCH, INC.
Street Address:	BUILDING 4, NO. 1690, CAI LUN ROAD
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City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15814246

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	1106989.00012
NAME OF SUBMITTER:	MIN WU
SIGNATURE:	/Min Wu/
DATE SIGNED:	05/09/2018

Total Attachments: 2
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Docket No. 1106989.00012

ASSIGNMENT

WHEREAS, we, Hui Wang, Fufa Chen, Fuping Chen, Jian Wang, Xi Wang, Xiaoyan Zhang, Yinuo Jin, Zhaowei Jia, Liangzhi Xie, Jun Wang and Xuejun Li, have invented certain new and useful inventions disclosed in U.S. Application No. 15/814,246, entitled "METHOD FOR CLEANING SEMICONDUCTOR WAFERS", filed November 15, 2017 for United States Letters Patent;

WHEREAS, ACM Research, Inc., a corporation organized and existing under the laws of the State of Delaware, having a place of business at Building 4, No. 1690, Cai Lun Road, Zhangjiang High-Tech Park, Pudong District, Shanghai 201203, China, the ASSIGNEE herein, desires to acquire the entire right to, title to, and interest in said inventions, applications, and Letters Patent to be granted and issued thereon;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over, and do hereby sell, assign, transfer, and set over to ASSIGNEE the entire right to, title to, and interest in said inventions, and said application and all applications claiming priority thereto including all utility filings and all divisions, continuations, and continuations-in-part thereof, and all United States Letters Patents which may be granted thereon and all reissues, reexaminations, and extensions thereof, and all priority rights under all available International Agreements, Treaties, and Conventions for the protection of intellectual property in its various forms in every participating country, all national and regional applications deriving therefrom, and all subsequent patents and divisional patents, and all applications for patents (including related rights such as utility-model registrations, inventor's certificates, and the like) heretofore or hereafter filed for improvements in any foreign countries, and all patents (including all continuations, continuations-in-part, divisions, extensions, renewals, substitutes, and reissues thereof) granted for said inventions in any foreign countries; and we hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to ASSIGNEE in accordance with the terms of this Assignment;

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith;

AND WE HEREBY further covenant and agree that we will communicate to ASSIGNEE any facts known to us respecting said inventions, testify in any legal proceeding, sign all lawful papers, execute all documents for subsequent patent filings, make all rightful oaths, and generally do everything possible to aid ASSIGNEE to obtain and enforce proper patent protection for said improvements in all countries.

NAME AND SIGNATURE OF ASSIGNOR		
Name: Hui Wang	Signature: H Wang	Date: 03/30/2018
Name: Fufa Chen	Signature:	Date: 03/30/2018
Name: Fuping Chen	Signature: Fuping CHEN	Date: [illegible]

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Name: Jian Wang	Signature: Jian Wang	Date: 2018.4.2.
Name: Xi Wang	Signature: Xi Wang	Date: 2018.3.30
Name: Xiaoyan Zhang	Signature: Xiao Yan Zhang	Date: 2018.3.30
Name: Yinuo Jin	Signature: Yinuo Jin	Date: 2018.3.30
Name: Zhaowei Jia	Signature: Zhaowei Jia	Date: 2018.4.16
Name: Liangzhi Xie	Signature: Liangzhi Xie	Date: 2018.4.18
Name: Jun Wang	Signature: Jun Wang	Date: 2018.3.30
Name: Xuejun Li	Signature: Xuejun Li	Date: 3.30